

## **REMARKS**

### **Present Status of the Application**

Present pending claims 6-14 are rejected. Specifically in Advisory Office Action, claims 6-14 remain in rejections. Applicants have amended independent claim 6 and added claims 15-16. After entry of amendments, claims 6-16 remain pending in the present application, and reconsideration of those claims is respectfully requested.

### **Discussion of Claim Rejections**

In response to Advisory Office Action, Applicants have amended claim 6 and added claim 15, and then respectfully traverse the rejections for at least the reason set forth below.

1. With respect to independent claim 6, the bump 226 is recited to have the smooth curving surface. This bump structure of the present invention is not disclosed by the stencil printable solder paste 36 of Degani.

Degani in Fig. 1 has stated that the bump 11 causes the problem and then suggests to use the stencil printable solder paste 36, which is a flat top surface, so as to contact the flat pad 37 (see Fig. 3). The stencil printable solder paste 36 is specifically not under reflow (col. 5, lines 41-44) although it will be reflowed at the end to have the solder joint 38 (col. 5, lines 57-62).

Therefore, Degani based on printing mechanism does not disclose the method of the present invention. Degani indeed considers different packaging issue and mechanism from the present invention.

2. For at least the same foregoing reasons, dependent claims 6-14 are not disclosed by Degani.

3. With respect to claims 15-16, as shown in FIG. 7, the chip may further have the conductive adhesive layer 228 on the metal layer 224, with lower melting point than that of the bump 226. As a result, after the chip 220 is attached to the substrate, the reflow process at lower temperature can be just applied on the conductive adhesive layer 228, so as to wrap the ball-like bump 226.

Degani does not specifically disclose the method and mechanism of the present invention as recited in claims 15-16.

For at least the foregoing reasons, Applicants respectfully submit that independent claims 6 and 15 patently define over the prior art references, and should be allowed. For at least the same reasons, dependent claims 7-14 and 16 patently define over the prior art references as well.

**CONCLUSION**

For at least the foregoing reasons, it is believed that all the pending claims 6-16 of the invention patently define over the prior art and are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Date :

May 5, 2008

Respectfully submitted,

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